

NLX2G66

Dual Bilateral Analog Switch / Digital Multiplexer

The NLX2G66 is a dual single pole, single throw (SPST) analog switch / digital multiplexer. This single supply voltage IC is designed with a sub-micron CMOS technology to provide low propagation delays (t_{PD}) and ON resistance (R_{ON}), while maintaining low power dissipation. This bi-lateral switch can be used with either analog or digital signals that may vary across the full power supply range from V_{CC} to GND.

Features

- Wide V_{CC} Operating Range: 1.65 V to 5.5 V
- OVT up to +5.5 V for Control Pin
- R_{ON} : Typically $< 5 \Omega$ at $V_{CC} = 4.5$ V and $I_S = 32$ mA
- Rail-to-Rail Input/Output
- High Speed, Typical $t_{PD} < 1$ ns at $V_{CC} = 4.5$ V and $C_L = 50$ pF
- High On-Off Output Voltage Ratio
- High Degree of Linearity
- Ultra-Small Pb-Free, Halide-Free, RoHS-Compliant Packages
- ESD Performance: > 5000 V HBM, > 400 V MM

Typical Applications

- Cell Phones, PDAs, MP3 and other Portable Media Players

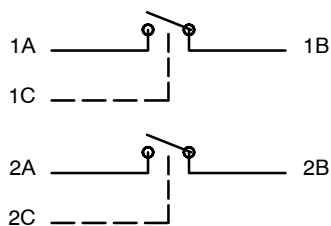


Figure 1. Analog Symbol

PIN ASSIGNMENTS

UDFN8	UQFN8-0.5P	Description
1	7	1A
2	6	1B
3	5	2C
4	4	GND
5	3	2A
6	2	2B
7	1	1C
8	8	V_{CC}

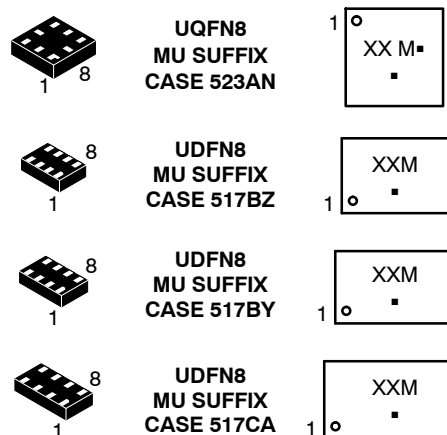
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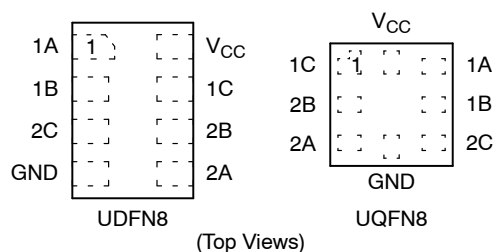
MARKING DIAGRAMS



XX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(*Note: Microdot may be in either location)

PIN ASSIGNMENTS



FUNCTION TABLE

Control Input (C)	Switch
L	OFF
H	ON

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

NLX2G66

Table 1. MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V_{CC}	Positive DC Supply Voltage	-0.5 to +7.0	V
V_S	Switch Input / Output Voltage (Pins 1A, 1B, 2A and 2B)	-0.5 to + V_{CC} + 0.5	V
V_I	Digital Control Input Voltage (Pins 1C and 2C)	-0.5 to +7.0	V
I_{OK}	I/O port diode current	±50	mA
I_{IK}	Control input diode current	-50	mA
$I_{I/O}$	Continuous DC Current Through Analog Switch	±100	mA
I_L	Latch-up Current, (Above V_{CC} and below GND at 125°C)	±100	mA
T_s	Storage Temperature	-65 to +150	°C
V_{ESD}	ESD Withstand Voltage: Human Body Model (HBM) Machine Model (MM)	≥ 5000 > 400	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 2. RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _S	Switch Input / Output Voltage (Pins 1A, 2A, 1B and 2B)		GND	V _{CC}	V
V _I	Digital Control Input Voltage (Pins 1C and 2C)		GND	5.5	V
T _A	Operating Temperature Range		−55	+125	°C
t _r , t _f	Input Transition Rise or Fall Time (ON/OFF Control Input)	V _{CC} = < 3.0 V	0	20	ns/V
		V _{CC} = ≥ 3.0 V	0	10	

Table 3. ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC}	Guaranteed Limit				Unit
				25°C		–55° to 125°C		
				Min	Max	Min	Max	
V _{IH}	High–Level Input Voltage, Control Input		1.65 to 1.95			V _{CC} x 0.65		V
			2.3 to 5.5			V _{CC} x 0.7		
V _{IL}	Low–Level Input Voltage, Control Input		1.65 to 1.95				V _{CC} x 0.35	V
			2.3 to 5.5				V _{CC} x 0.30	
I _I	Input Leakage Current, Control Input	V _I = V _{CC} or GND	5.5		±0.1		±1	μA
I _{S(ON)}	ON–State Switch Leakage Current	V _{IS} = V _{CC} or GND, V _I = V _{IH} , V _{OS} = Open	5.5		±0.1		±1	μA
I _{S(OFF)}	OFF–State Switch Leakage Current	V _{IS} = V _{CC} and V _{OS} = GND, or V _{IS} = GND and V _{OS} = V _{CC} GND, V _I = V _{IL} .	5.5		±0.1		±1	μA
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	5.5		1.0		10	μA
ΔI _{CC}	Supply Current Change	V _I = V _{CC} – 0.6	5.5				500	μA
C _I	Control Input Capacitance		5				3.0	pF
C _{I/O(Off)}	Switch OFF Input / Output Capacitance	See Figure 3	5				6.0	pF
C _{I/O(On)}	Switch ON Input / Output Capacitance	See Figure 4	5				13	pF

NLX2G66

Table 4. SWITCHING CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC}	Guaranteed Limit		Unit
				-55° to 125°C		
				Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to B, B to A	C _L = 30 pF, R _L = 1 kΩ	1.8		6.5	ns
			2.5		3.3	
		C _L = 50 pF, R _L = 500 Ω	3.3		2.5	
			5.0		2.2	
T _{EN} (t _{PZH} , t _{PZL})	Enable Time, C to Analog Output (A or B)	C _L = 50 pF, R _L = 500 Ω See Figure 6	1.8		10	ns
			2.5		6.5	
			3.3		5.5	
			5.0		4.9	
T _{DIS} (t _{PZH} , t _{PZL})	Disable Time, C to Analog Output (A or B)	C _L = 50 pF, R _L = 500 Ω See Figure 6	1.8		9.0	ns
			2.5		7.2	
			3.3		6.5	
			5.0		6.0	

Table 5. ANALOG SWITCH CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC}	25°C	-55° to 125°C		Unit
				Typ	Min	Max	
R _{ON}	On-Resistance	V _{IS} = V _{CC} or GND, V _I = V _{IH} , See Figure 2	I _S = 4 ma	1.65	12	30	Ω
			I _S = 8 ma	2.3	9	20	
			I _S = 24 ma	3.0	7.5	15	
			I _S = 32 ma	4.5	5.5	13	
R _{ON(peak)}	Peak On-Resistance	V _{IS} = GND to V _{CC} ; V _I = V _{IH} , See Figure 2	I _S = 4 ma	1.65	74.5	220	Ω
			I _S = 8 ma	2.3	20	75	
			I _S = 24 ma	3.0	11.5	25	
			I _S = 32 ma	4.5	7.5	17	
ΔR _{ON}	On-Resistance Mismatch between Switches	V _{IS} = GND to V _{CC} ; V _I = V _{IH} , See Figure 2	I _S = 4 ma	1.65		8.0	Ω
			I _S = 8 ma	2.3		5.0	
			I _S = 24 ma	3.0		3.0	
			I _S = 32 ma	4.5		2.0	
BW	Bandwidth (f _{-3dB})	R _L = 50 Ω, C _L = 5 pF, f _{IN} = Sine Wave See Figure 8	1.65			> 270	MHz
			2.3			> 270	
			3.0			> 270	
			4.5			> 270	

Table 5. ANALOG SWITCH CHARACTERISTICS (continued)

Symbol	Parameter	Conditions	V _{CC}	25°C	Unit
				Typ	
ISO _{Off}	Off-Channel Feedthrough Isolation	R _L = 600 Ω, C _L = 50 pF, f _{IN} = 1 MHz Sine Wave See Figure 9	1.65	-70	dB
			2.3	-70	
			3.0	-70	
			4.5	-70	
		R _L = 50 Ω, C _L = 5 pF, f _{IN} = 1 MHz Sine Wave See Figure 9	1.65	-60	
			2.3	-60	
			3.0	-60	
			4.5	-60	
XTalk	Crosstalk Between Switches	R _L = 600 Ω, C _L = 50 pF, f _{IN} = 1 MHz Sine Wave See Figure 10	1.65	-100	dB
			2.3	-100	
			3.0	-100	
			4.5	-100	
		R _L = 50 Ω, C _L = 5 pF, f _{IN} = 1 MHz Sine Wave See Figure 10	1.65	-90	
			2.3	-90	
			3.0	-90	
			4.5	-90	
	Feedthrough Noise, Control to Switch	R _L = 600 Ω, C _L = 50 pF, f _{IN} = 1 MHz Square Wave, t _r = t _f = 2 ns, See Figure 11	1.65	10	mV _{pp}
			2.3	10	
			3.0	10	
			4.5	15	
THD	Total Harmonic Distortion	C _L = 50 pF, R _L = 50 Ω, f _{IN} = 600 Hz to 20 KHz Sine Wave, See Figure 12	2.3	0.025	%
			3.0	0.015	
			4.5	0.01	

Table 6. POWER DISSIPATION CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC}	25°C	Unit
				Typ	
C _{PD}	Power Dissipation Capacitance	f = 10 MHz	1.65	8.0	pF
			2.3	8.9	
			3.0	9.6	
			4.5	10.9	

NLX2G66

Table 7. DEVICE ORDERING INFORMATION

Device Order Number	Package	Shipping [†]
NLX2G66AMUTCG (In Development)	UQFN8–0.5P, 1.6 mm x 1.6 mm (Pb–Free)	3000 / Tape & Reel
NLX2G66DMUTAG	UDFN8–0.5P, 1.95 mm x 1.0 mm (Pb–Free)	3000 / Tape & Reel
NLX2G66DMUTCG	UDFN8–0.5P, 1.95 mm x 1.0 mm (Pb–Free)	3000 / Tape & Reel
NLX2G66EMUTCG (In Development)	UDFN8–0.4P, 1.6 mm x 1.0 mm (Pb–Free)	3000 / Tape & Reel
NLX2G66FMUTCG (In Development)	UDFN8–0.35P, 1.45 mm x 1.0 mm (Pb–Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

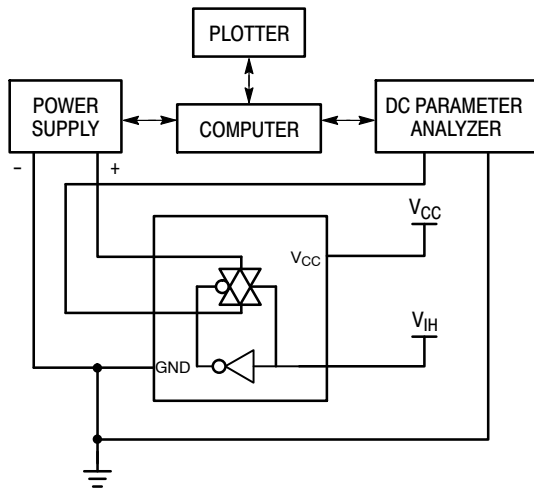


Figure 2. On Resistance Test Set-Up

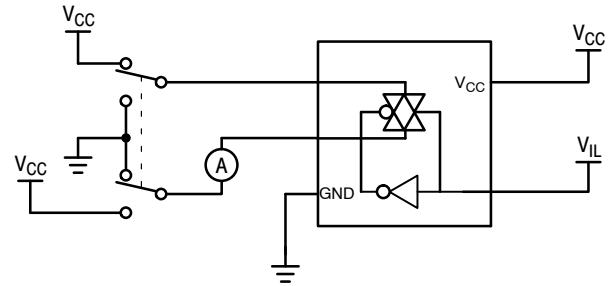


Figure 3. Maximum Off-Channel Leakage Current Test Set-Up

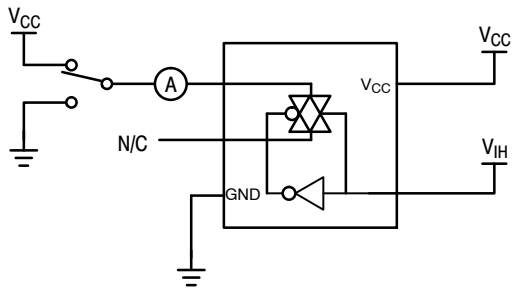


Figure 4. Maximum On-Channel Leakage Current Test Set-Up

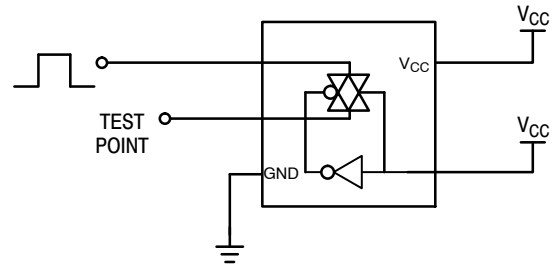


Figure 5. Propagation Delay Test Set-Up

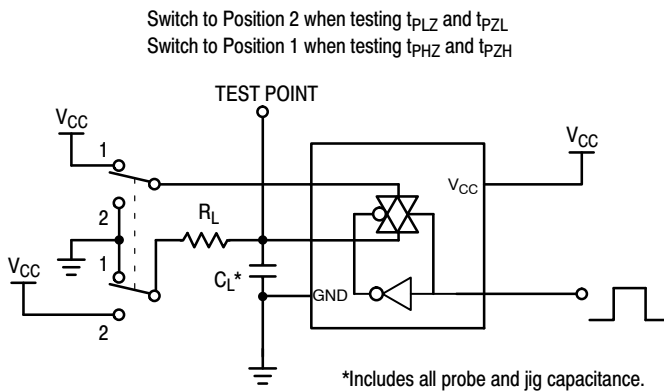


Figure 6. Propagation Delay Output Enable/Disable Test Set-Up

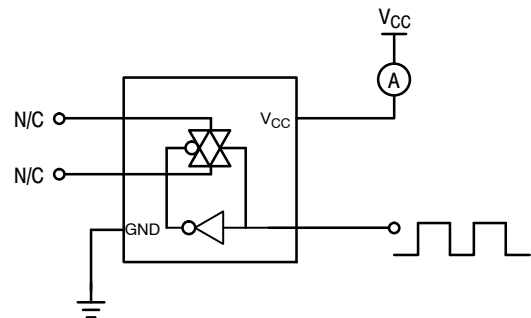


Figure 7. Power Dissipation Capacitance Test Set-Up

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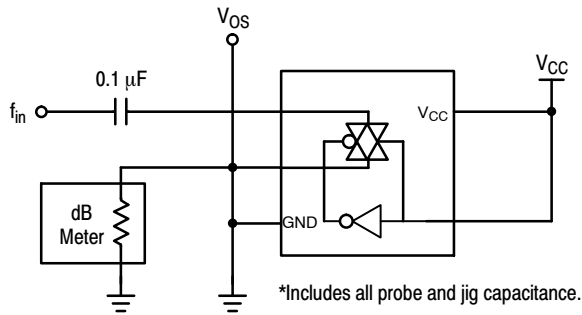


Figure 8. Maximum On-Channel Bandwidth Test Set-Up

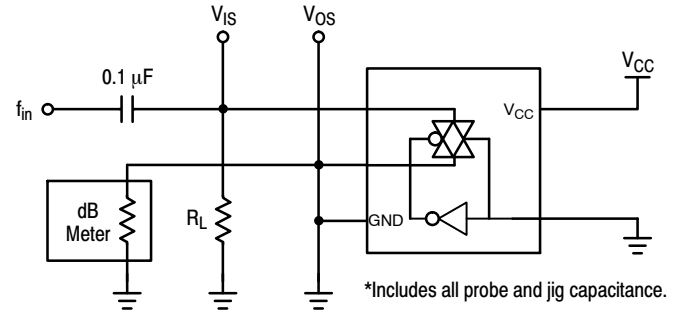


Figure 9. Off-Channel Feedthrough Isolation Test Set-Up

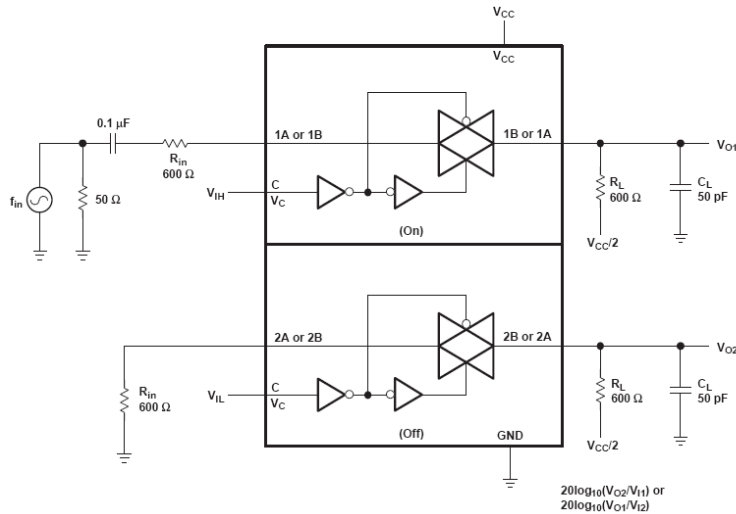


Figure 10. Crosstalk (between Switches)

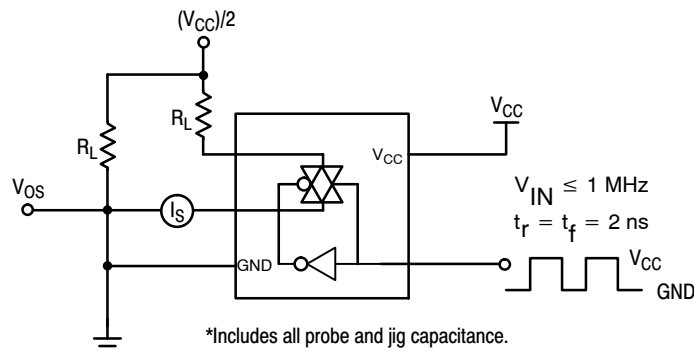


Figure 11. Feedthrough Noise, ON/OFF Control to Analog Out, Test Set-Up

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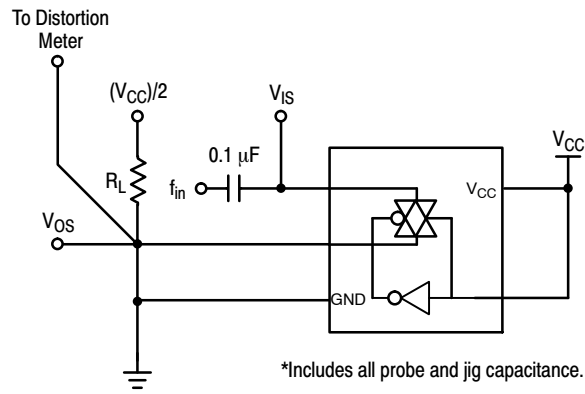


Figure 12. Total Harmonic Distortion Test Set-Up

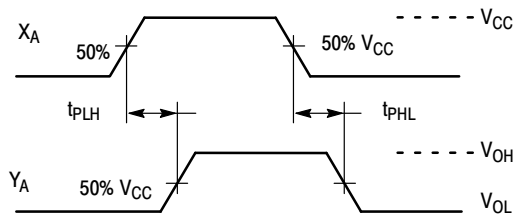


Figure 13. Propagation Delay, Analog In to Analog Out Waveforms

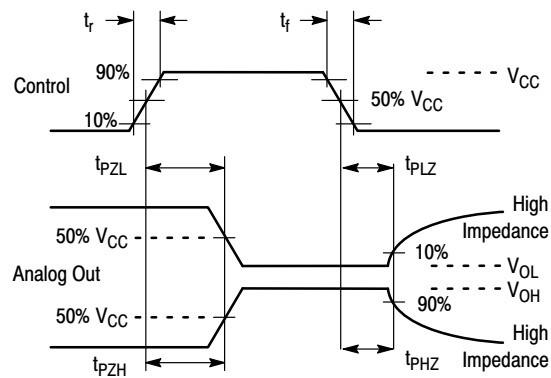
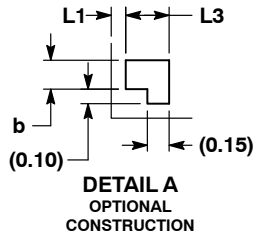
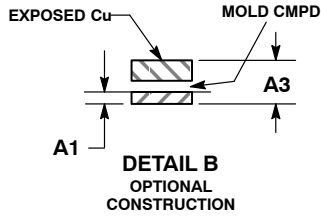
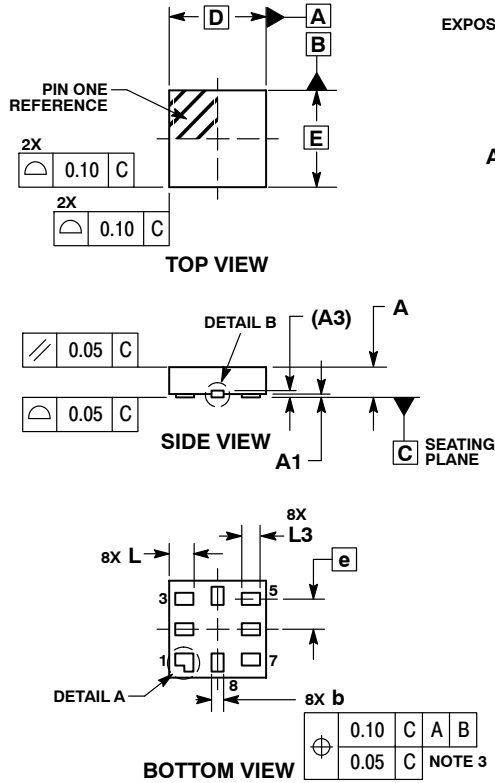


Figure 14. Propagation Delay, ON/OFF Control

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PACKAGE DIMENSIONS

UQFN8
MU SUFFIX
CASE 523AN
ISSUE O

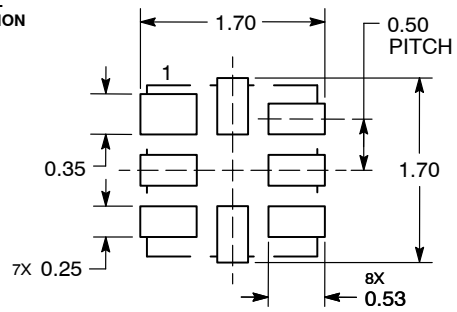


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	1.60	BSC
E	1.60	BSC
e	0.50	BSC
L	0.35	0.45
L1	---	0.15
L3	0.25	0.35

SOLDERING FOOTPRINT*



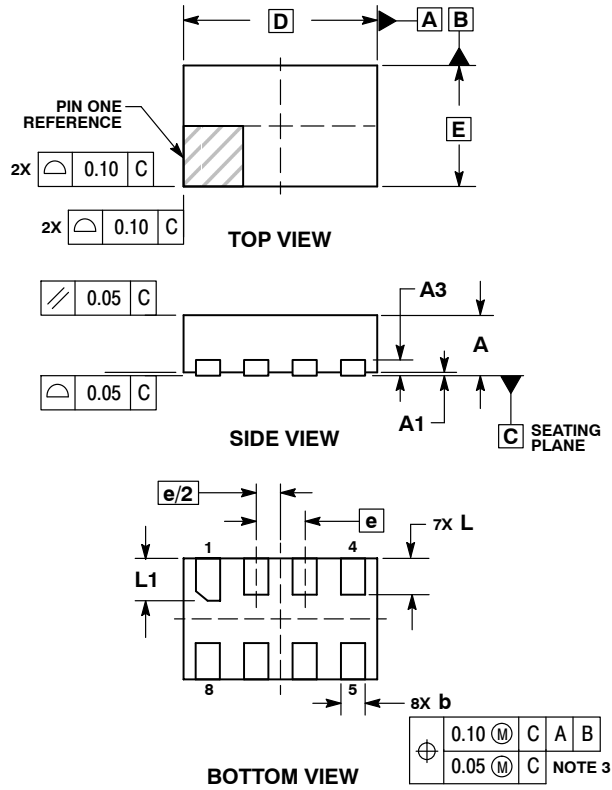
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NLX2G66

PACKAGE DIMENSIONS

UDFN8 1.6x1.0, 0.4P
CASE 517BY
ISSUE O

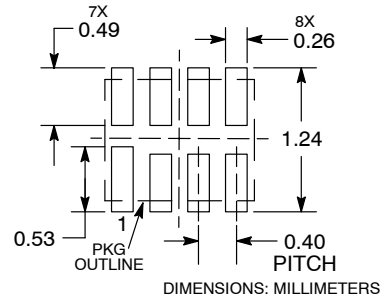


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	1.60	BSC
E	1.00	BSC
e	0.40	BSC
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*

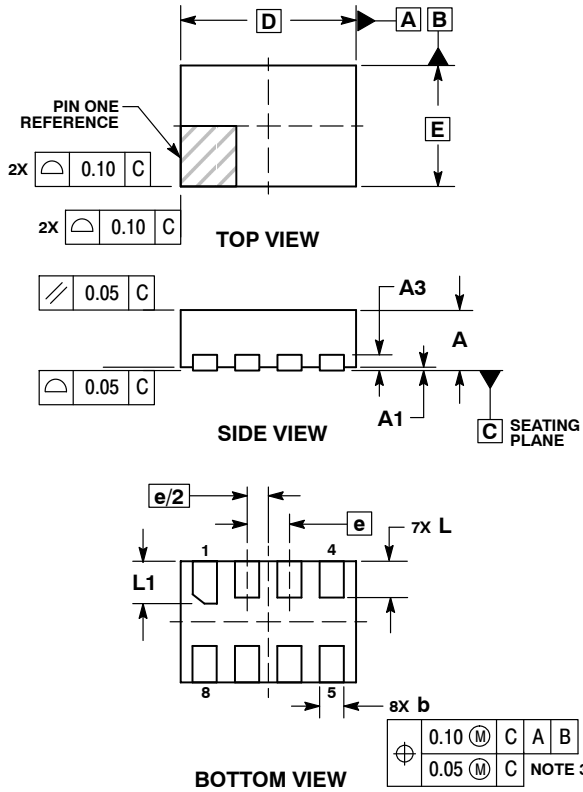


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NLX2G66

PACKAGE DIMENSIONS

UDFN8 1.45x1.0, 0.35P
CASE 517BZ
ISSUE O

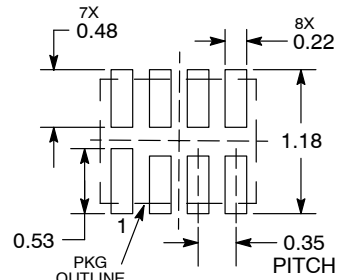


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*



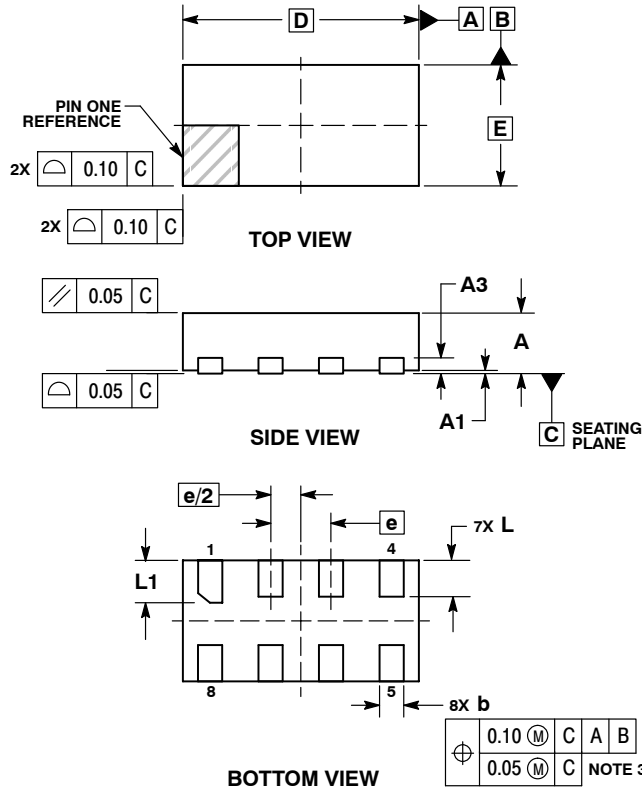
DIMENSIONS: MILLIMETERS

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NLX2G66

PACKAGE DIMENSIONS

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CASE 517CA
ISSUE O

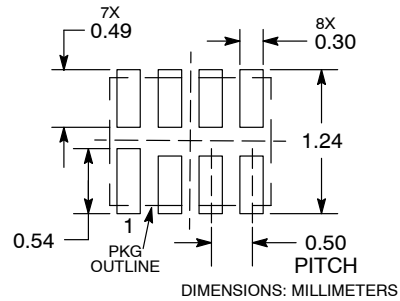


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
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4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	1.95	BSC
E	1.00	BSC
e	0.50	BSC
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*



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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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